



Material Content Data Sheet



Sales Product Name		TLE5009A16 E1210		Issued		25. January 2018		
MA#		MA001597774						
Package		PG-TDSO-16-1		Weight*		67.88 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.681	1.00	1.00	10034	10034
leadframe	inorganic material	silicon	7440-21-3	0.007	0.01		96	
		non noble metal	titanium	7440-32-6	0.033	0.05	479	
		non noble metal	chromium	7440-47-3	0.098	0.14	1437	
		non noble metal	copper	7440-50-8	32.380	47.70	47.90	477028
wire	noble metal	gold	7440-57-5	0.119	0.18	0.18	1760	1760
encapsulation	organic material	carbon black	1333-86-4	0.065	0.10		955	
		plastics	epoxy resin	-	3.500	5.16	51563	
		inorganic material	silicondioxide	60676-86-0	28.843	42.49	47.75	424916
leadfinish	non noble metal	tin	7440-31-5	1.198	1.76	1.76	17643	17643
plating	noble metal	silver	7440-22-4	0.840	1.24	1.24	12378	12378
glue	plastics	epoxy resin	-	0.029	0.04		428	
		inorganic material	silicondioxide	60676-86-0	0.058	0.09	855	
		plastics	acrylic resin	-	0.029	0.04	0.17	428
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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